		Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility. **Adobe Reader version 7.0.5 is required to complete this declaration.**

IPC-1752-2 v1.02	IPC Web Site for Information on IPC-1752 Standard **http://www.ipc.org/IPC-175x**	**Form Type ***	**Declaration Class ***

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	**Response Date ***	Response Document ID	
Contact Name *	Title - Contact	**Phone - Contact ***	**Email - Contact ***		
Authorized Representative *	Title - Representative	**Phone - Representative ***	**Email - Representative ***	Supplier Comments or URL for Additional Information	

	Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Type
	Alternate Recommendation				Alternate Item Comments				

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature C	Max Time at Peak Temperature seconds	Number of Reflow Cycles
Comments					

RoHS Material Composition Declaration

Declaration Type *

RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

RoHS Declaration *

Supplier Acceptance

Exemptions: The items on this form meet the specifications of the RoHS Definition above, except for the following application-specific exemptions. Check the appropriate boxes below for the applicable exemptions for the item.

- ☐ **1**. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp
- ☐ **2a.** Mercury in straight flourescent lamps for general purposes not exceeding 10 mg in halophosphate lamps
- ☐ **2b**. Mercury in straight flourescent lamps for general purposes not exceeding 5 mg in triphosphate lamps with a normal lifetime
- ☐ **2c**. Mercury in straight flourescent lamps for general purposes not exceeding 8 mg in triphosphate lamps with long lifetime
- ☐ **3**. Mercury in straight flourescent lamps for special purposes
- ☐ **4**. Mercury in other lamps not specifically mentioned in this list
- ☐ **5**. Lead in glass of cathode ray tubes, electronic components and flourescent tubes
- ☐ **6a**. Lead as an alloying element in steel containing up to 0.35% lead by weight
- ☐ **6b**. Lead as an alloying element in aluminum containing up to 0.4% lead by weight
- ☐ **6c.**. Lead as an alloying element in copper containing up to 4% lead by weight
- ☐ **7a**. Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead)
- ☐ **7b**. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications

- ☐ **7c**. Lead in electronic ceramic parts (e.g. piezoelectronic devices)
- ☐ **8.** Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending. Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances
- ☐ **9.** Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators
- ☐ **10a.** DecaBDE in polymeric applications
- ☐ **10b.** Lead in lead-bronze bearing shells and bushes
- ☐ **11**. Lead used in compliant pin connector systems
- ☐ **12**. Lead as a coating material for a thermal conduction module c-ring
- ☐ **13a.** Lead in optical and filter glass
- ☐ **13b.** Cadmium in optical and filter glass
- ☐ **14.** Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight
- ☐ **15.** Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

***Required Field**   CAS Registry Number(R) is a Registered Trademark of the American Chemical Society   Form enabled by Adobe

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +P Inserts a New Part   +M Inserts a new Material   +C Inserts a new Substance Category   +S Inserts a new Substance   - Deletes the element line

	Item/SubItem Name		Homogeneous Material	Weight	Unit of Measure		Level	Substance Category		Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance -	Tolerance +	PPM

* Required Field   CAS Registry Number(R) is a Registered Trademark of the American Chemical Society   Form enabled by Adobe

Homogeneous Material Composition Declaration for Electronic Products

Requester Instructions: The requester can optionally include additional substance categories and substances that must be declared for the item on this form. This is in addtion to JIG Level A and JIG Level B substances already included for the JIG section. The requester should enter additional substance categories and then enter name of the substance and the CAS number. These entries will be accessible to the supplier via Level drop-down by selecting "Requester".   Use the Load "Requester" and Test button to view the entries, just select "Requester" in the Level drop-down list in the previous section.

	Substance Category		Substance	CAS